

Note: '()' correspond to the letters used in the product bulletin
Click here for the 3D model.

| Dimensions |  |
| :--- | :--- |
| Chip Size | 5045 |
| L | $12.7 \mathrm{~mm}+0.4 \mathrm{~mm}$ |
| W | $11.5 \mathrm{~mm}+0.6 \mathrm{~mm}$ |
| T | $6.5 \mathrm{~mm}+0.4 \mathrm{~mm}$ |
| F | 0.5 mm NOM |

## Packaging Specifications

Packaging
T\&R
Packaging Quantity
600

| General Information |  |
| :--- | :--- |
| Series | SMP253 250 VAC |
| Dielectric | Metallized Paper |
| Style | SMD Chip |
| RoHS | Yes |
| Termination | Tin |
| Safety Class | Y2 |
| Qualifications | ENEC, cULus |
| AEC-Q200 | Yes |
| Typical Component Weight | 1.6 g |


| Specifications |  |
| :--- | :--- |
| Capacitance | 3900 pF |
| Capacitance Tolerance | $20 \%$ |
| Voltage DC | 1500 VDC |
| Voltage AC | 250 VAC |
| Temperature Range | $-40 /+100^{\circ} \mathrm{C}$ |
| Rated Temperature | $100^{\circ} \mathrm{C}$ |
| Dissipation Factor | $1.3 \% 1 \mathrm{kHz}$ |
| Insulation Resistance | 12 GOhms |
| Max dV/dt | $2000 \mathrm{~V} / \mathrm{us}$ |

